



TH235-2

Non Silicone Thermal Putty

Description

TH235-2 is a dispensable non silicone based thermally conductive putty. This putty is soft, extrudable, low bleed and nonflowable. It is designed for very good thermal conduction with high electrical insulation.

Features

- High compressible
- Dispensable
- Silicone free

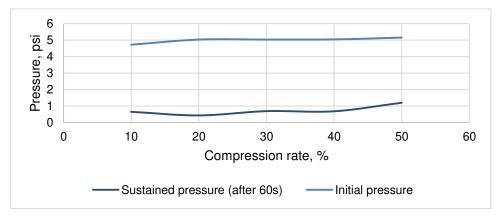
Applications

Dispensable thermally conductive silicone-based putty for use as thermal interface material for electronic component.

Properties	Typical Value	Typical Value Unit	
Color	Light blue	-	PEN 10
Specific gravity	3.0	g/cm ³	PEN 14
Viscosity, 25°C	245,000	cP	PEN 44
Extrusion rate, 2.5mm orifice, 50psi, 25°C	8.5	g/min	PEN 107
Flow test, 45° incline	No flow	mm	PEN 15
Thermal conductivity	4.0	W/m.K	ASTM D5470
Volatile content			
a) 30-150°C	0.45	%	PEN 92
Operating temperature	-40 to 120	°C	PEN 92
Flammabiliy,UL94	V-0	-	PEN 55
Bleed test, 100°C/100hrs, blot width	45	mm	PEN 129

^{*} The values above are tested based on batch to batch basis. These values are not used as a basis for preparing specifications.

Compression deflection



Compression rate (%)	Unit	10	20	30	40	50
Initial pressure	psi	4.72	5.03	5.03	5.04	5.15
Sustained pressure (after 60s)	psi	0.65	0.43	0.69	0.68	1.2

Remark: Specimen dimension- 25mm x 25mm x 1.0mm

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^{*} PEN is referring to Penchem's standard test method; ASTM is for test reference only.

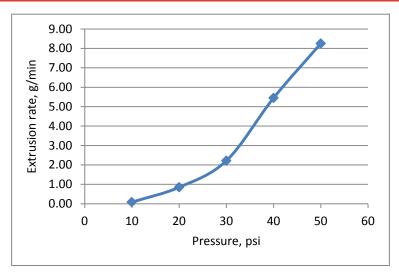
^{*} Viscosity was measured by CAP2000+ viscometer, CAP06, 5rpm, 25.0°C.





Non Silicone Thermal Putty

Extrusion Rate vs Dispensing Pressure



Pressure, psi	10	20	30	40	50
Extrusion rate (g/min)	0.08	0.85	2.22	5.45	8.25

Remark: Dispensing nozzle: ID - 2.5mm

Guideline of Use

- 1) Wear rubber glove when handling the non silicone putty.
- 2) Scoop a quantity of the non silicone putty from the container using a stainless steel spatula.
- 3) Work and knead the putty around electronic part and circuit by hand.
- 4) This product may be dispensed by pneumatic dispenser or other dispensing equipment with an appropriate needle. Increasing the dispensing temperature (eg. 60°C) can ease the dispensing process. The user is responsible to determine the suitability of the product for all intended uses.
- 5) Wipe off any excess putty with a piece of dry cloth. Further cleaning of residues may be achieved by wiping with cloth wetted with isopropanol.

Features

Tightly close original packaging of unused product and store at room temperature. Avoid prolong exposure to sunlight.

Shelf life:12 months

Applications

- 10ml syringe
- 30ml syringe
- 500g plastic jar

Other packaging enquiry, please contact our sales department.

Environment, Health & Safety

This product is intended for industrial use only. For more safety information, please refer to Product Safety Data Sheet (SDS).

General Information

 All right reserved. This information in this document is subjected to change without notice.

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